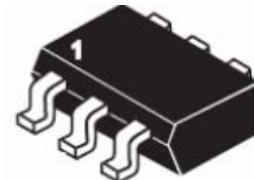
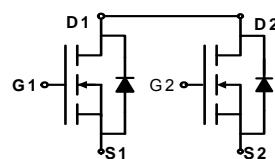
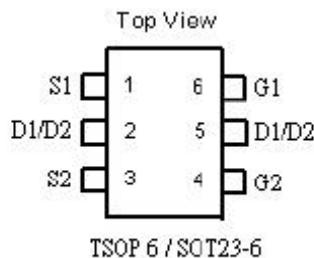


8205
Dual N CHANNEL High Density Trench MOSFET

TYPE	BVDSS	RDS(ON)	ID
8205	20V	25mΩ@VGS=4.5V	5A
		40mΩ@VGS=2.5V	5A


Green Product

PIN DESCRIPTION



FEATURES

- High Density cell trench design for low R
- Rugged and reliable
- Surface Mount package
- Lead Free Available(Green Product)

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DSS}	Drain-Source Voltage (V _{GS} =0V)	20	V
V _{GSS}	Gate- source Voltage	±12V	V
I _D (a)	Drain Current (continuous) at T _C = 25 °C	5	A
I _D	Drain Current (continuous) at T _C = 100 °C	2.4	A
I _{DM} (b)	Drain Current (pulsed)	24	A
P _{tot}	Total Dissipation at T _C = 25 °C	1.25	W
T _{stg}	Storage Temperature	- 55~175	°C
T _j	Max. Operating Junction Temperature		

(a) Current limited by package

(b) Pulse width limited by safe operating area

THERMAL DATA

R _{thj-amb}	Thermal Resistance Junction-ambient	Max	100	°C / W
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8205

Dual N CHANNEL High Density Trench MOSFET

ELECTRICAL CHARACTERISTICS ($T_{case} = 25^\circ C$ unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
BV_{DSS}	Drain-source Breakdown Voltage	$I_D = 250 \mu A$, $V_{GS} = 0V$	20			V
I_{DSS}	Zero Gate Voltage Drain Current ($V_{GS} = 0V$)	$V_{DS} = 16V$			1	μA
I_{GSS}	Current ($V_{DS} = 0V$)	$V_{GS} = \pm 12V$			± 100	nA

ON

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	0.5	0.7	1.2	V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS} = 4.5V$, $I_D = 5A$		23	25	$m\Omega$
		$V_{GS} = 2.5V$, $I_D = 5A$		34	40	$m\Omega$

DYNAMIC

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{DS} = 10V$, $f = 1 MHz$, $V_{GS}=0V$		595		PF
C_{oss}	Output Capacitance			140		PF
C_{rss}	Reverse Transfer Capacitance			125		PF

8205
Dual N CHANNEL High Density Trench MOSFET
ELECTRICAL CHARACTERISTICS (continued)
SWITCHING ON

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
td (on)	Turn-on Delay Time	VDD =10V , ID = 6A , Rg=3Ω VGS =4.5V		3.5		ns
tr	Rise Time			13.5		ns
Qg	Total Gate Charge	VDD = 10V , ID =6 A , VGS = 4.5V		21		nc
Qgs	Gate-Source Charge			1.3		nc
Qgd	Gate-Drain Charge			3.3		nc

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
td (off)	Turn-off Delay Time	VDD = 10V , ID =6A , Rg=3Ω VGS =4.5V		32		ns
tf	Fall Time			6.6		ns

SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
IS	Continuous source-drain diode current	Tc= 25°C			5	A
Trr	Body diode reverse recovery Time	IF=6A , di/dt = 100A/us , Tj=25°C		14		nS
Qrr	Body diode reverse recovery charge			5		nC
VSD	Forward On Voltage	ISD =1.0 A , VGS = 0V		0.78	1.2	V

B

A

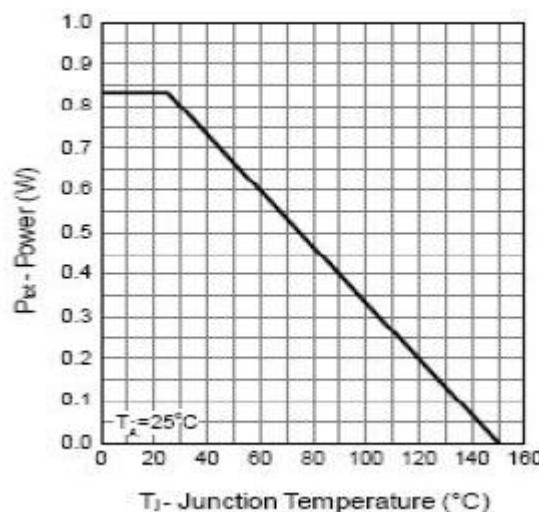
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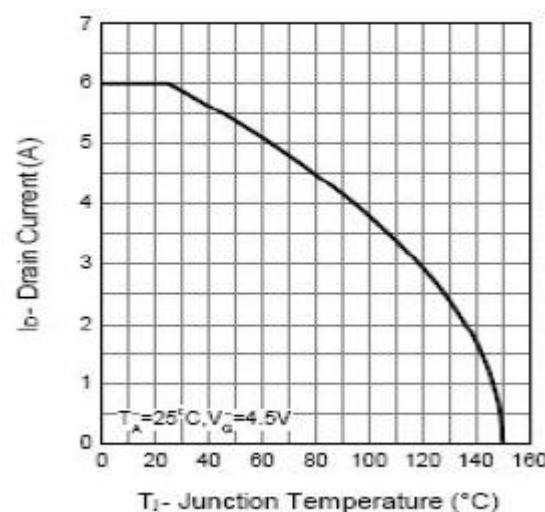
Dual N CHANNEL High Density Trench MOSFET

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

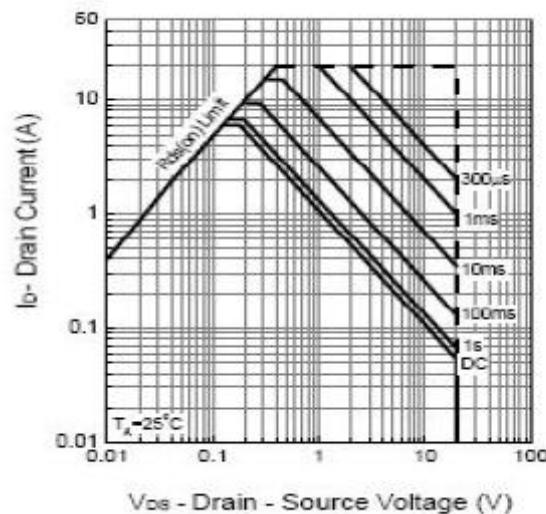
Power Dissipation



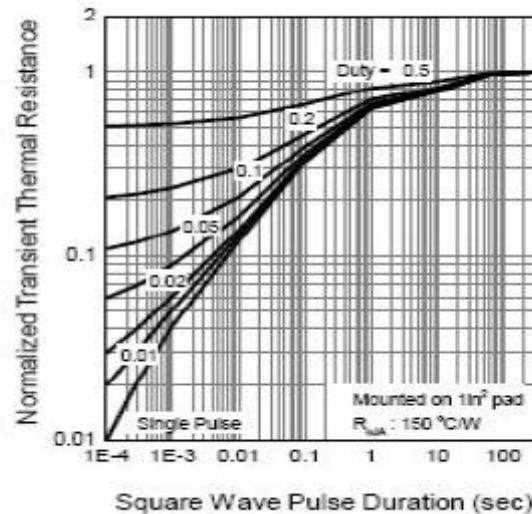
Drain Current



Safe Operation Area

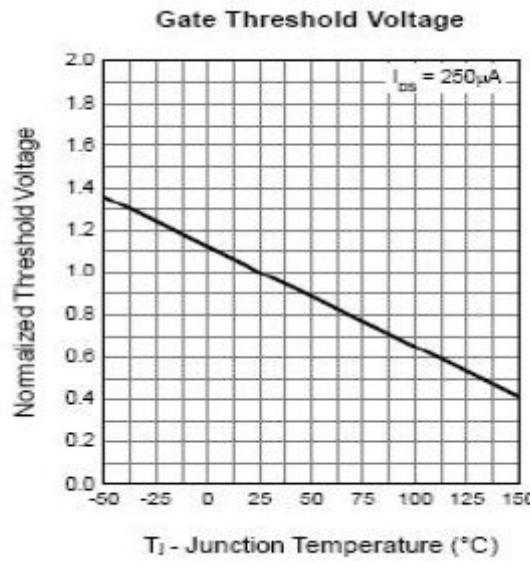
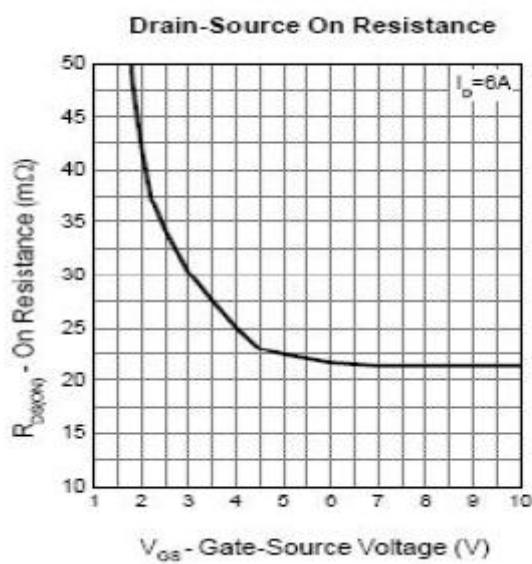
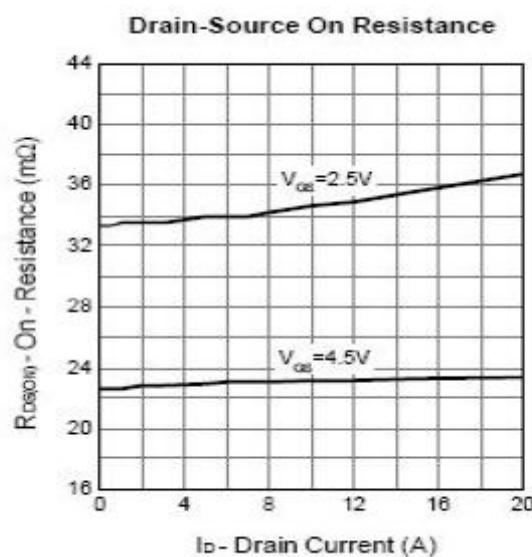
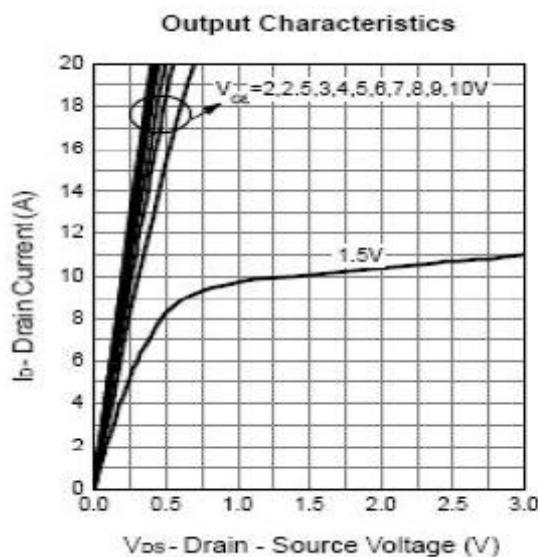


Thermal Transient Impedance



8205

Dual N CHANNEL High Density Trench MOSFET



8205

Dual N CHANNEL High Density Trench MOSFET

